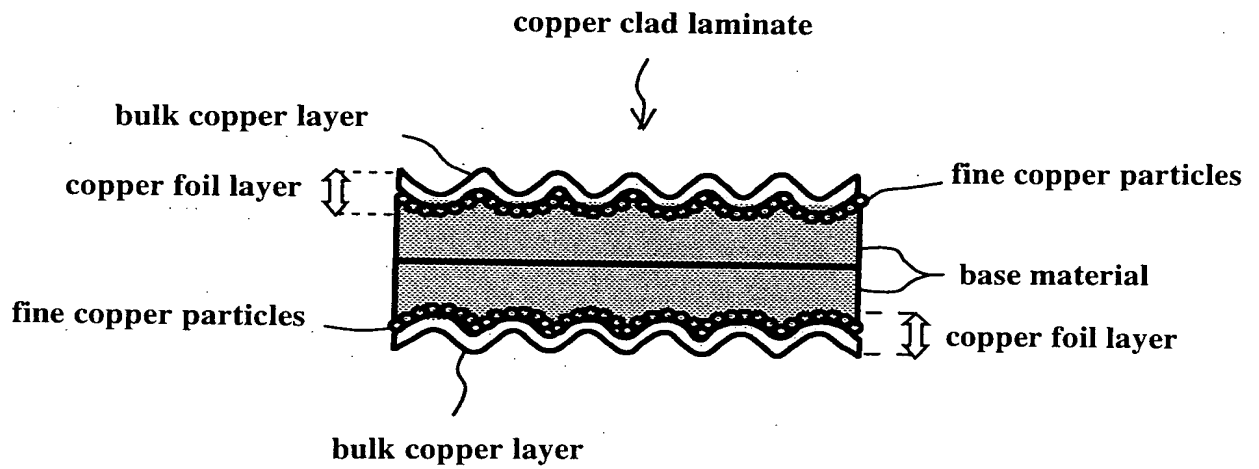
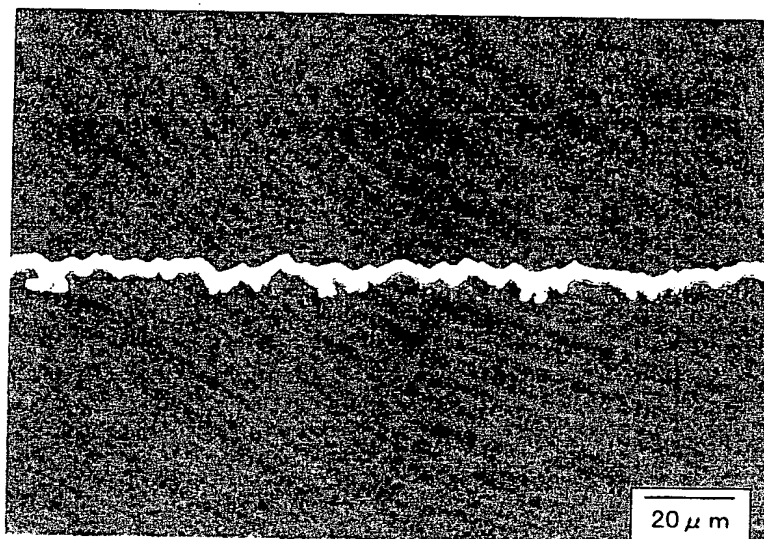


FIG. 1



09855382.051501

FIG. 2



098539 05101
T05T50 28E5850

FIG. 3

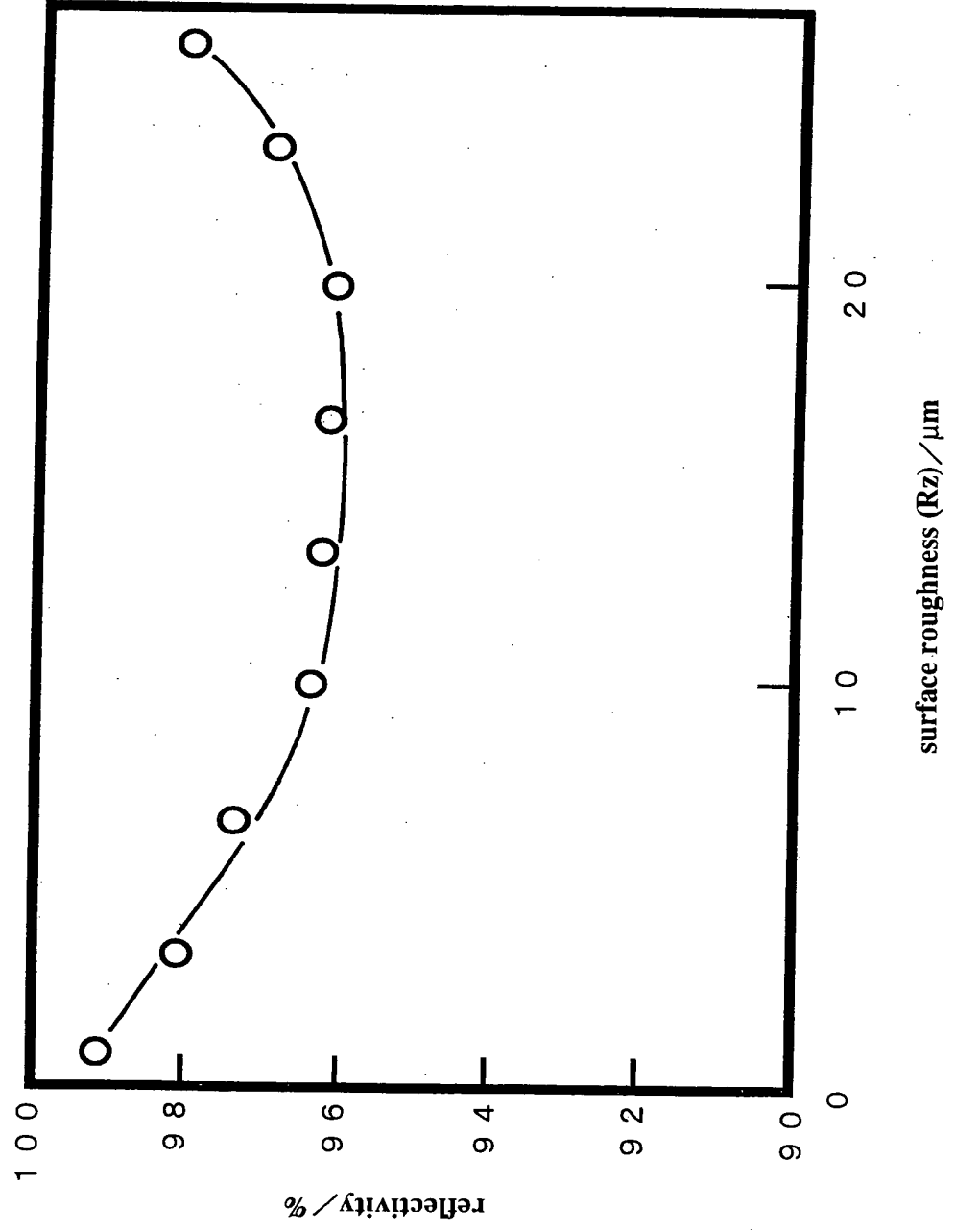
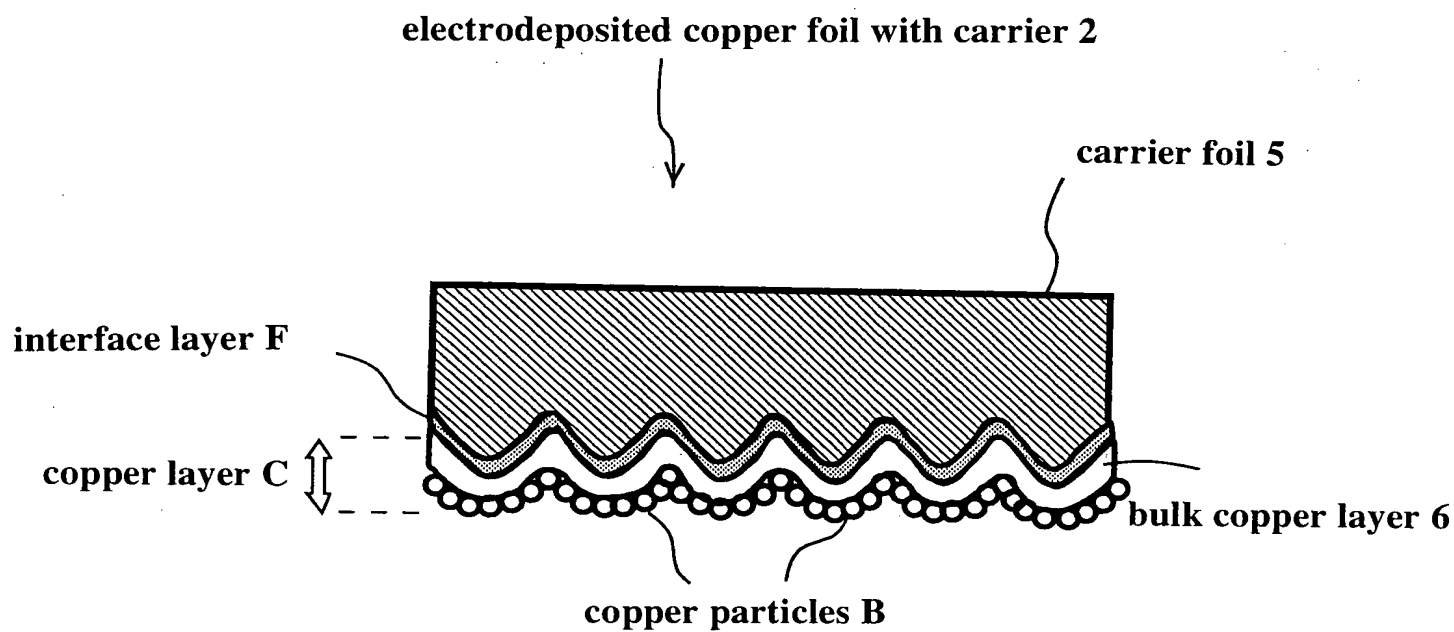


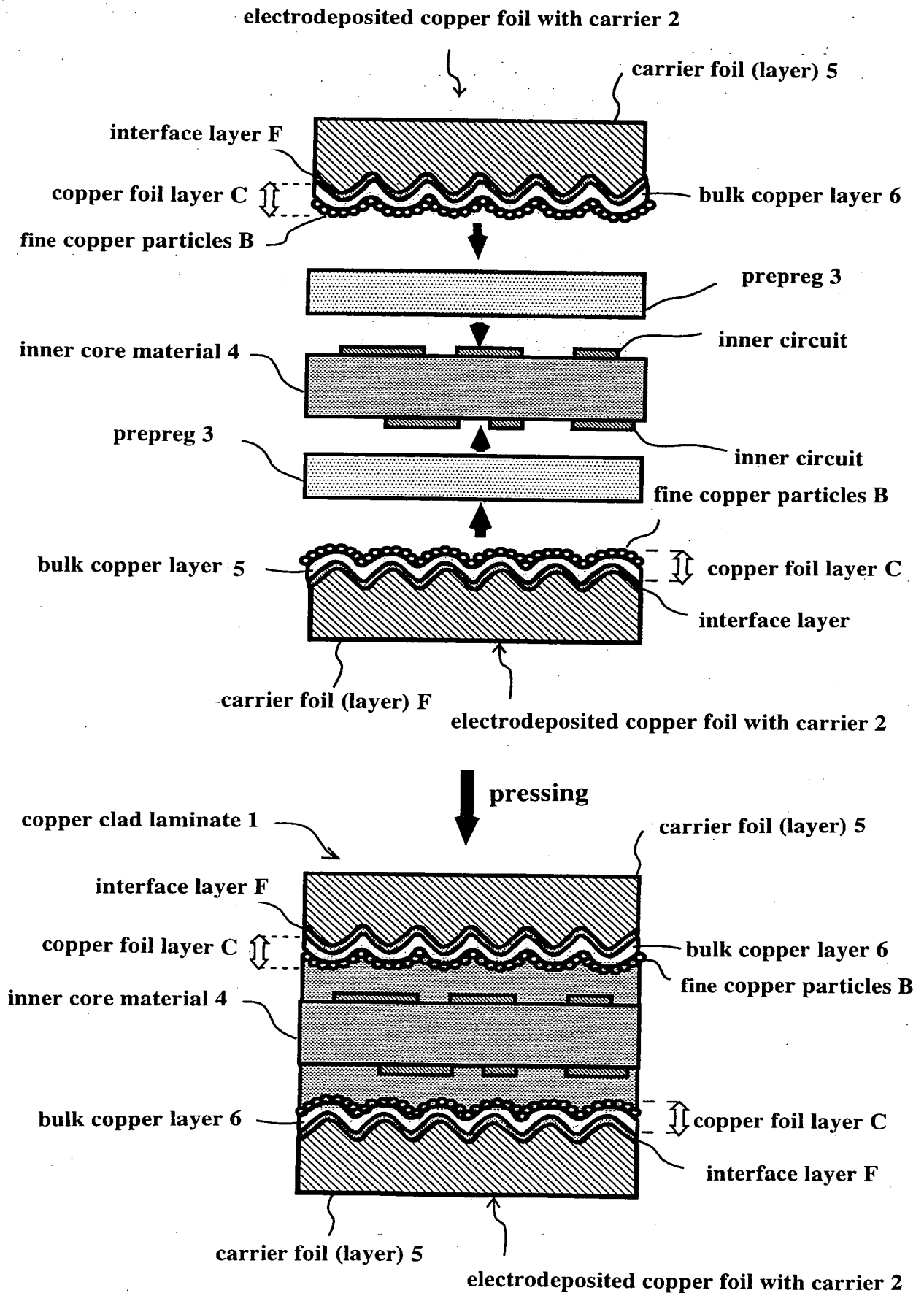
FIG. 4



09055382 051501
T05T50 2825860

FIG. 5

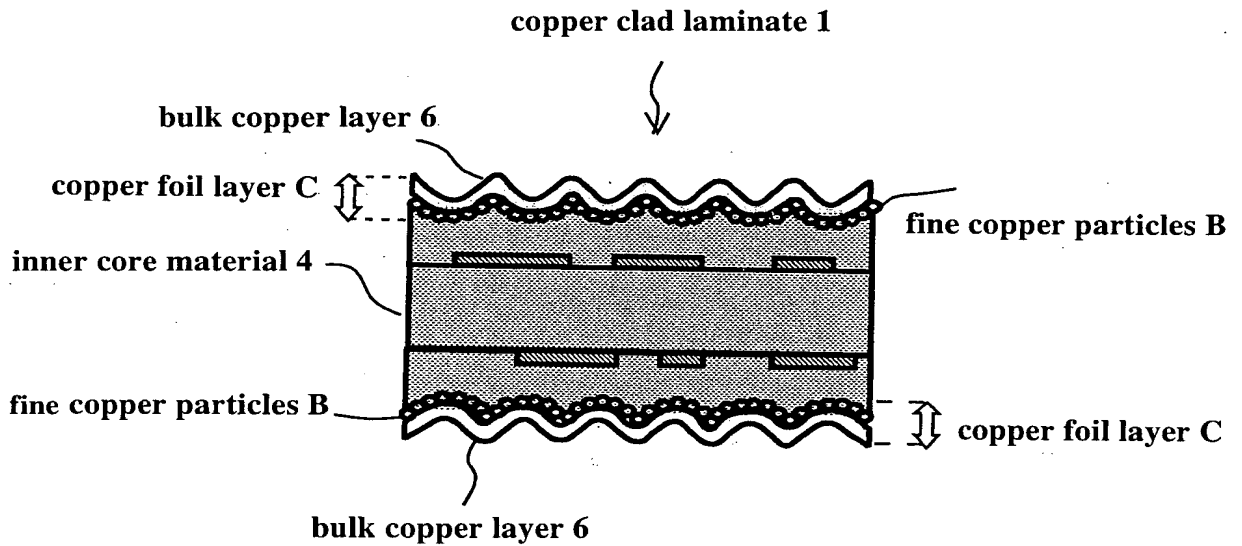
(a) Manufacturing of copper clad laminate



09855382 051504

FIG. 6

(b) Peeling of Carrier Foil



(c) Laser Treatment for Forming Holes

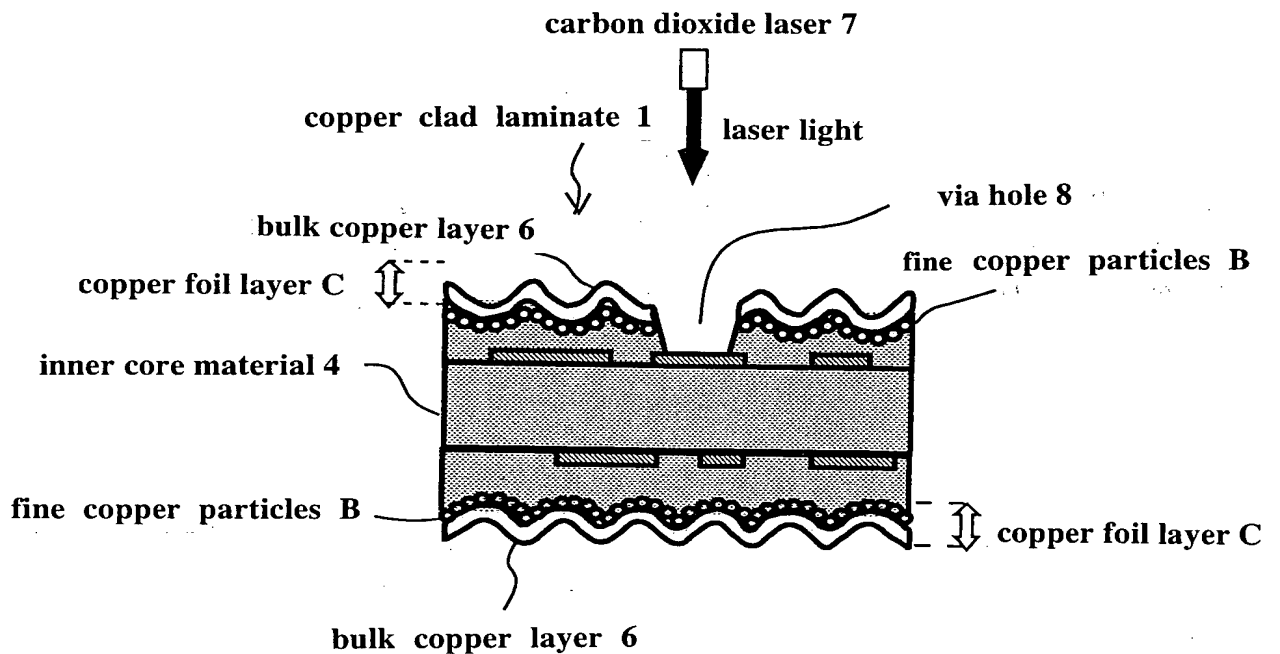
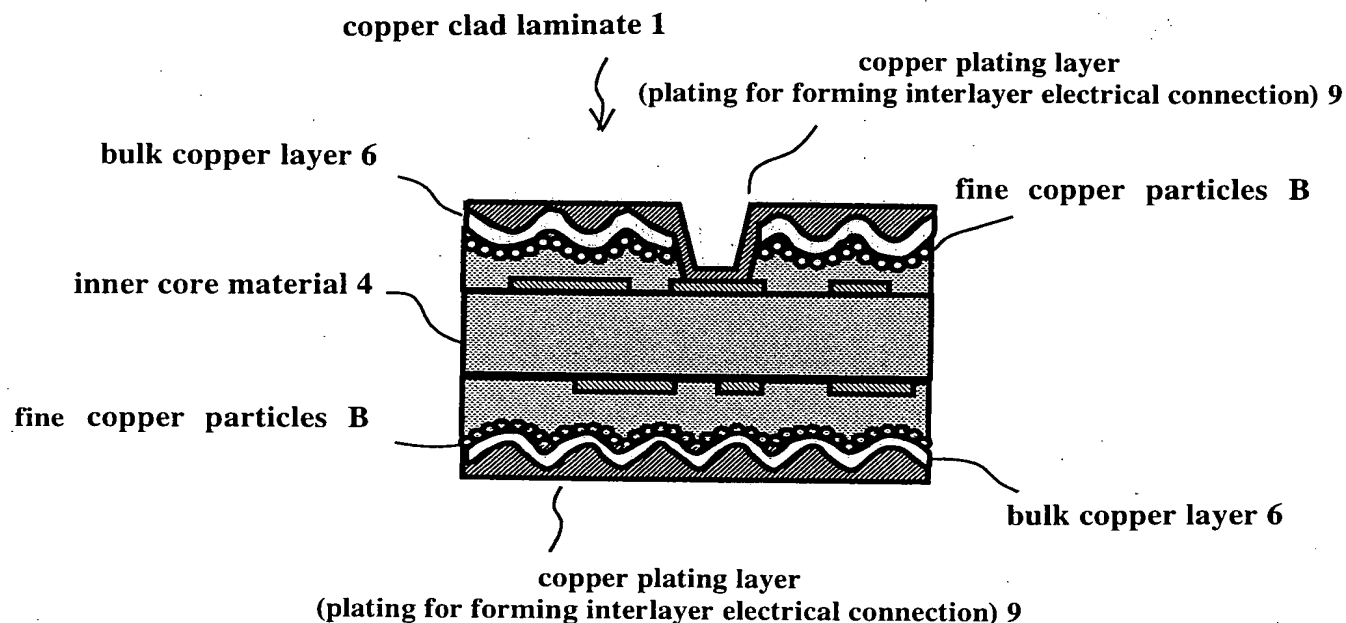


FIG. 7

(d) Copper Plating for Forming Interlayer Electrical Connection



(e) Forming Etching Resist Layers

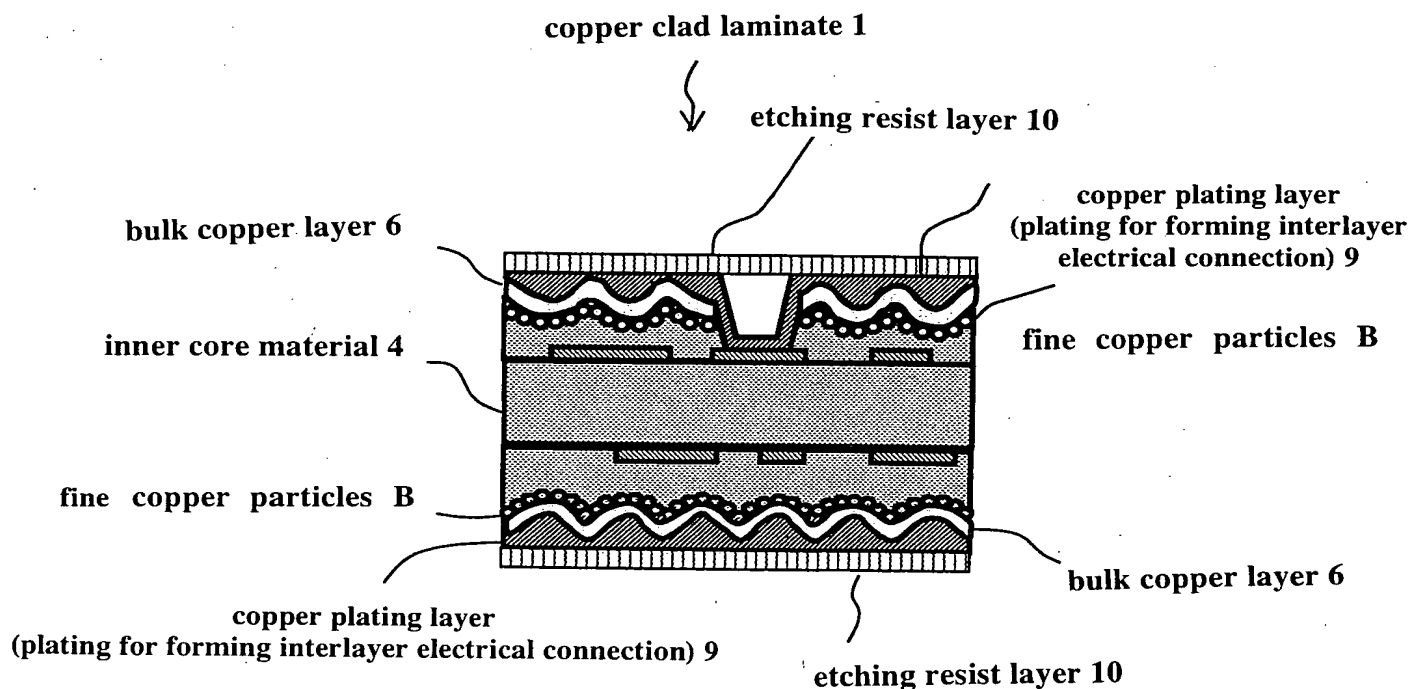
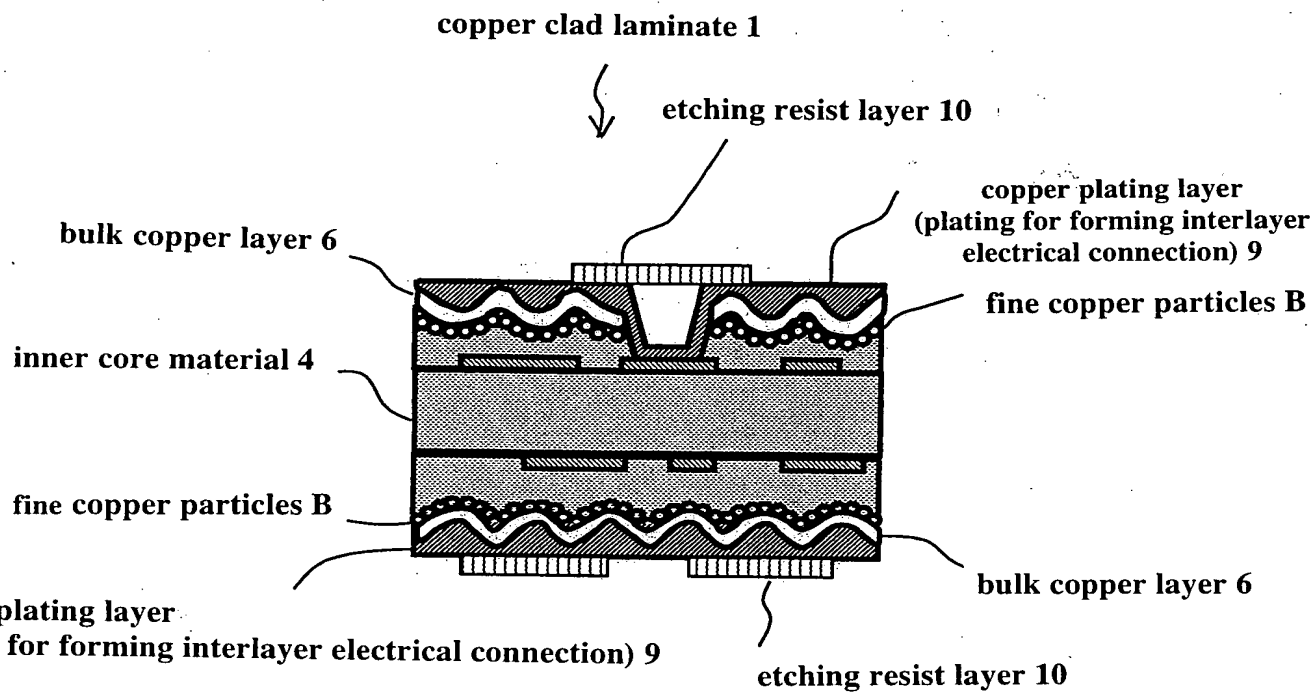
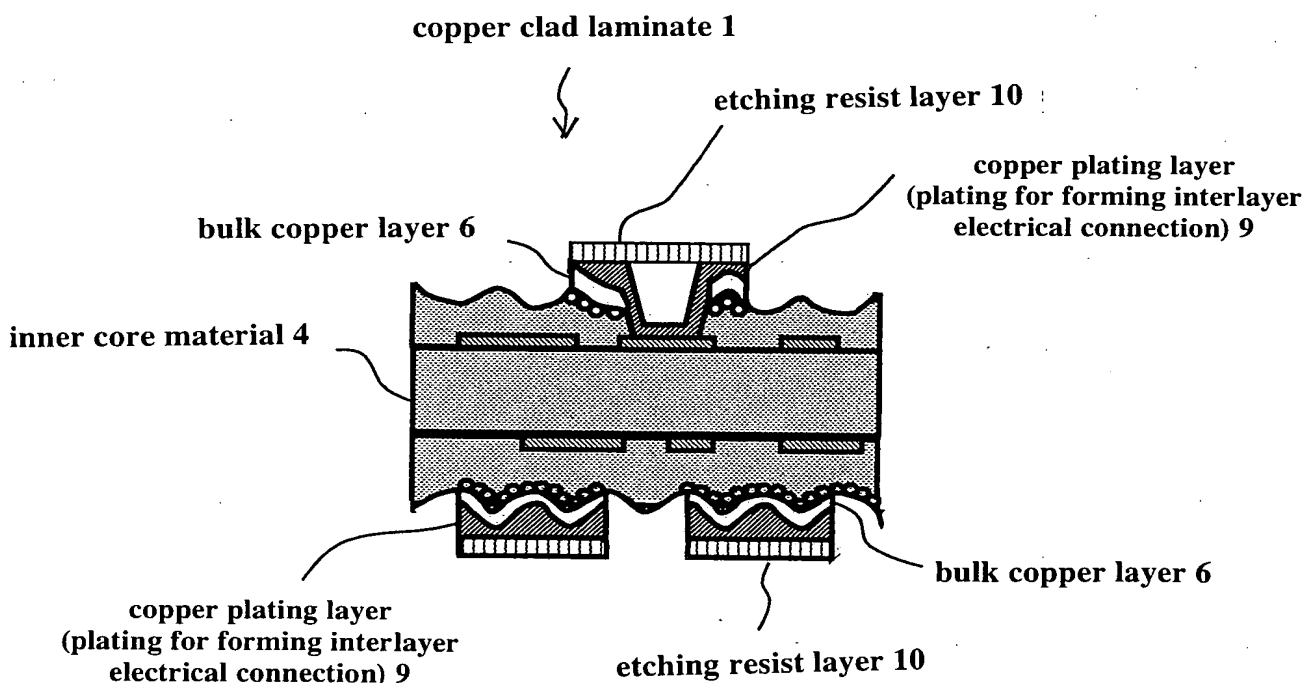


FIG. 8

(f) Exposing and Developing the Etching Resist Layers



(g) Copper Etching



F05150 2855860

FIG. 9

(h) Peering of Etching Resist Layers

